

TK PASTE

CR-2800

Conductive bonding for grounding and shielding Low silver, low temperature curing

CR-5200

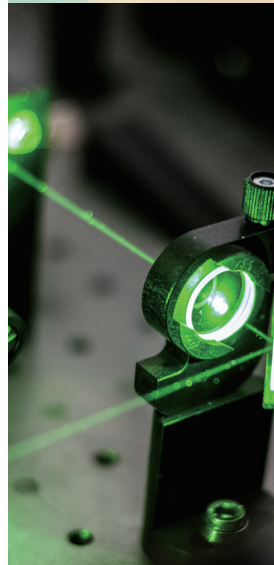
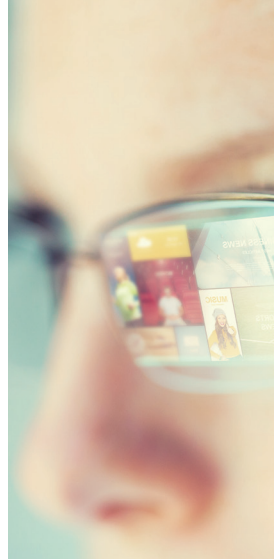
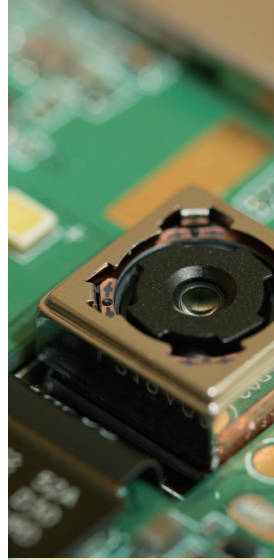
Conductive bonding of weak heat-resistant modules and components Low temperature curing

CN-7120·CN-7122S

Conductive bonding without heating Room temperature drying

CR-3520·CR-3990

Conductive bonding with high strength and high heat dissipation High reliability



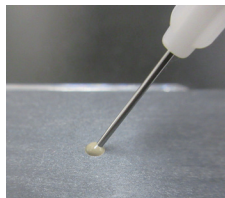
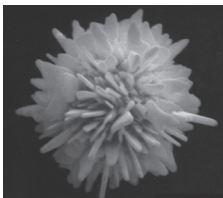
Conductive bonding
for grounding and shielding

CR-2800



Low silver, low temperature curing

- Silver content 50wt.%
- Low silver, low specific gravity, low cost
- Low outgas, low temperature curing
- Ideal for ground conductive bonding for grounding and shielding



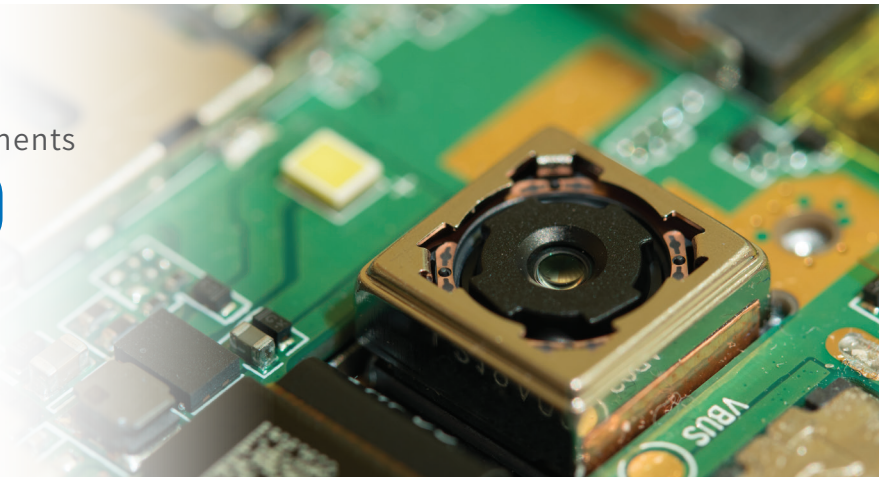
Apply with a dispenser



	CR-2800
Feature	Low silver 50wt.%
Binder	Epoxy resin
Curing condition	90°C x 60min
Specific resistivity	$6 \times 10^{-3} \Omega \cdot \text{cm}$
Viscosity (@25°C, 5rpm)	30Pa·S
Storage condition	Below -10°C

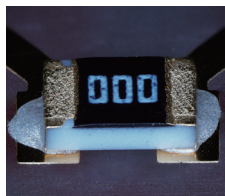
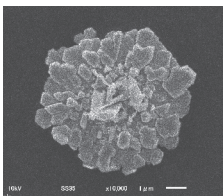
Conductive bonding of
weak heat-resistant components

CR-5200



Low temperature curing

- Suppress deterioration of resistance due to galvanic corrosion*
- Good conductivity with tin (Sn) and nickel (Ni)
- Stable contact resistance by TK silver powder
- Suitable for module assembly and component mounting with low heat resistance



Mounting of chip components



	CR-5200
Feature	Low temp. curing, good resistivity
Binder	Epoxy resin
Curing condition	100°C x 60min
Specific resistivity	$3 \times 10^{-4} \Omega \cdot \text{cm}$
Viscosity (@25°C, 5rpm)	30Pa·S
Storage condition	Below -10°C

*Galvanic corrosion is a corrosion phenomenon caused by the transfer of electrons between dissimilar metals with different potentials. When a low-potential metal (Sn or Ni) is bonded with a conductive adhesive (Ag), corrosion is accelerated under high temperature and high humidity conditions, resulting in a significant increase in resistance.

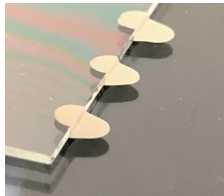
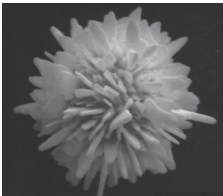
Conductive bonding
without heating

CN-7120 CN-7122S



Room temperature drying

- No heating required, drying at room temperature
- Provides conductivity after assembly
- Ideal for grounding applications in LCD touch panels and wearable devices.
- Quick-drying type CN-7120 and slow-drying type CN-7122S are available.



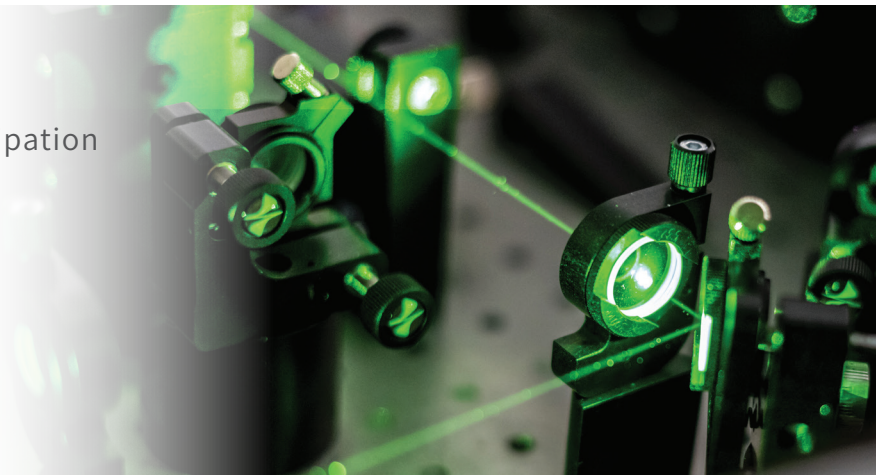
Ground from ITO glass surface



	CN-7120	CN-7122S
Feature	Quick drying	Slow drying
Binder	Thermoplastic resins	
Drying condition	25°C x 60min	40°C x 20min or 25°C x 2hrs
Specific resistivity	5x10 ⁻⁴ Ω·cm	
Viscosity (@25°C, 5rpm)	27Pa·S	10Pa·S
Storage condition	Below -10°C	

Conductive bonding with
high strength and heat dissipation

CR-3520 CR-3990

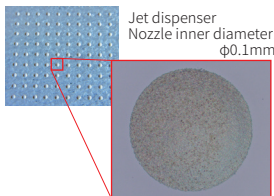


High reliability

- High heat dissipation (20W/mK), good dispense applicability CR-3520
- Strong adhesive strength (30MPa), good property under high temperature CR-3990
- Suitable for applications that require high reliability.



Good dispensability



Jet dispenser
Nozzle inner diameter:
φ0.1mm

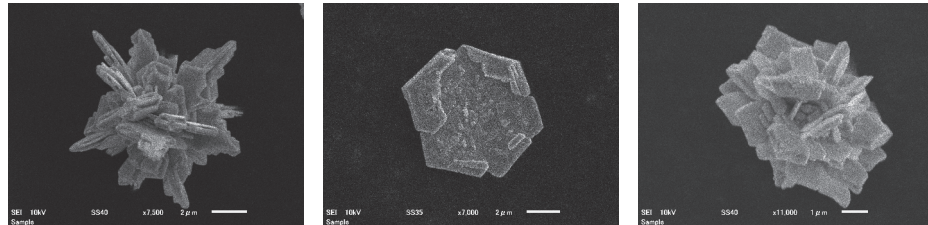
Suitable for fine dispensing



	CR-3520	CR-3990
Feature	Good heat dissipation	High strength
Binder	Epoxy resin	
Curing condition	130°C x 30min → 180°C x 60min Recommend step cure to reduce voids	
Specific resistivity	5x10 ⁻⁵ Ω·cm	2x10 ⁻³ Ω·cm
Viscosity (@25°C, 5rpm)	20Pa·S	18Pa·S
Storage condition	Below -10°C	

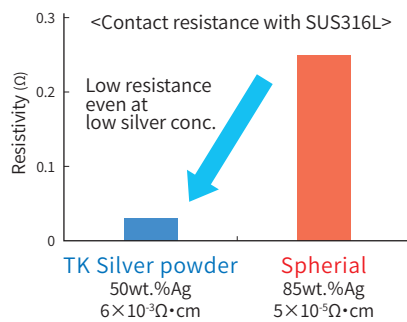
What's TK PASTE?

01 | TK silver powder with perfect control of silver shape and particle size is used.

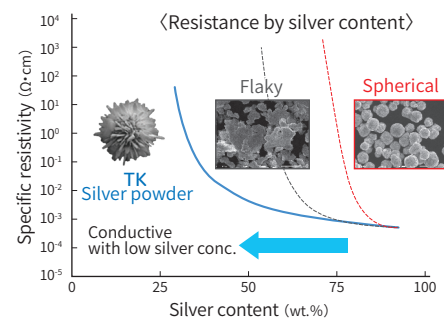


02 | Realizes various functions such as low resistance, sparse silver powder and high reliability.

• TK silver powder has low contact resistance.

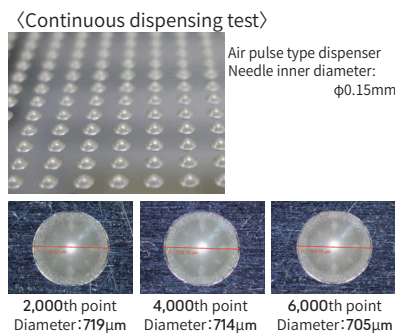


• TK silver powder has low contact resistance.

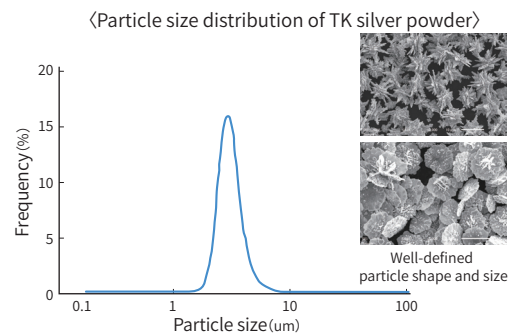


03 | Good dispensing performance

• Stable dispensing without clogging with small diameter nozzles.



• TK silver powder can be controlled with uniform size.



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